# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

| HP ProDesk 680 G2 MT Business PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Acbel EPA85</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel. (see Figure 1 below)
2. Disconnect SATA data & power cables from MB and ODD & HDD. (see Figure 2-7 below)
3. Remove ODD or HDD from chassis. (see Figure 8-11 below)
4. Disconnect PSU cables from chassis. (see Figure 12-14 below)
5. Disconnect FIO bles from chassis. (see Figure 15-18 below)
6. Disconnect other cables, and remove them from chassis. (see Figure 19-22 below)
7. Remove the Memory from MB. (see Figure 23 below)
8. Remove HeatSink from chassis and disassemble HeatSink. (see Figure 24-26 below)
9. Remove the CPU and battery from chassis. (see Figure 27-29 below)
10. Remove MB and Front Bezel from chassis. (see Figure 30-32 below)
11. Remove FIO and speaker from the chassis. (see Figure 33-34 below)
12. Remove system fan from the chassis. (see Figure 35 below)
13. Remove PSU from the chassis. (see Figure 36-37 below)
14. Remove PSU cover (see Figure 38-41 below)
15. Remove PSU FAN (see Figure 42-44 below)
16. Remove PSU PCB (see Figure 45-46 below)
17. Remove componet from PCB (see Figure 47 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel

Figure 2 Disconnect SATA cables from the MB

Figure 3 Disconnect SATA cable from HDD

Figure 4 Disconnect SATA cable from ODD

Figure 5 Disconnect Power SATA cable from the MB

Figure 6 Disconnect Power SATA cable from HDD

PSG instructions for this template are available at EL-MF877-01
Figure 7 Disconnect Power SATA cable from ODD

Figure 8 Press the HDD’s latch on HDD cage

Figure 9 Remove the HDD from cage

Figure 10 Press the ODD’s latch on ODD cage

Figure 11 Remove the ODD from cage

Figure 12 Disconnect CPU Power cable from the MB
<table>
<thead>
<tr>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>13</td>
<td>Disconnect MB Power cable from the MB</td>
</tr>
<tr>
<td>14</td>
<td>Disconnect PSU fan cable from the MB</td>
</tr>
<tr>
<td>15</td>
<td>Disconnect USB3.0 cable from the MB</td>
</tr>
<tr>
<td>16</td>
<td>Disconnect USB2.0 cable from the MB</td>
</tr>
<tr>
<td>17</td>
<td>Disconnect audio cable from the MB</td>
</tr>
<tr>
<td>18</td>
<td>Disconnect LED &amp; power switch cable</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 19 Disconnect speaker cable from the MB

Figure 20 Remove all the cables from this hook

Figure 21 Disconnect HS fan cable from the MB

Figure 22 Disconnect system fan cable from the MB

Figure 23 Remove the Memory from MB

Figure 24 Loose the screws and remove heat sink
Figure 25 Loose the screws from the CPU HeatSink

Figure 26 Remove the fan from the CPU HeatSink

Figure 27 Rotate CPU socket handle and open it up

Figure 28 Remove the CPU from MB
Figure 29 Remove the battery from MB

Figure 30 Loose MB screws from chassis

Figure 31 Remove MB from chassis

Figure 32 Remove Front Bezel from chassis

Figure 33 Loose screws of Front I/O and remove FIO

Figure 34 Loose screws of speaker and remove speaker
Figure 35 Loose screws of system fan and remove system fan

Figure 36 Loose screws of PSU

Figure 37 Remove PSU from chassis

Figure 38 Cut the cable tie

Figure 39 Remove screw for bottom

Figure 40 Remove screw for top

PSG instructions for this template are available at EL-MF877-01
Figure 41 Remove power supply cover

Figure 42 Remove power cable

Figure 43 Remove FAN screw

Figure 44 Remove AC inlet screw

Figure 45 Remove FG screw

Figure 46 Remove PCB screw
Fig 47 Remove capacitor for PCB